

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A manufacturing method for a device in which some or all of plural elements formed on a first substrate, are transferred to a second substrate, and some or all of the transferred elements are used to manufacture the device, the method comprising:

~~\_\_\_\_\_ a first process for forming a~~ separation layer on said first substrate;

~~\_\_\_\_\_ a second process for forming many~~ elements on said separation layer;

~~\_\_\_\_\_ a third process for adhering the elements to be transferred on said first~~  
substrate, to said second substrate via an adhesive layer;

~~\_\_\_\_\_ selectively radiating light onto said separation layer, to execute at least one of~~  
internal exfoliation and interfacial exfoliation of said separation layer;

~~\_\_\_\_\_ a fourth process for exerting a force acting in a direction to separate said first~~  
substrate and said second substrate on the separation layer between said first substrate and  
said second substrate from one edge of those substrates, to execute at least one of internal  
exfoliation and interfacial exfoliation ~~in the layer and/or on an interface~~ of the separation  
layer; and

~~\_\_\_\_\_ a fifth process for separating said first substrate from which the transfer of~~  
elements has been completed, from said second substrate.

2. (Original) A manufacturing method for a device according to claim 1, wherein the transfer of the elements from said first substrate to said second substrate comprising a step of collectively transferring all the elements formed on said first substrate.

3. (Currently Amended) A manufacturing method for a device according to claim 1, further comprising:

\_\_\_\_\_ ~~a sixth process for~~ forming after separating said first substrate from said second substrate, a thin film element providing substrate by providing a heat fusion sheet containing heat sealing adhesive on said elements which have been transferred to said second substrate;

\_\_\_\_\_ ~~a seventh process for~~ superposing a final substrate so that it contacts ~~with said~~ heat fusion sheet of said thin film element providing substrate, selectively irradiating light only on the area of said elements to be transferred, and adhering only said elements to be transferred onto the final substrate for device forming; and

\_\_\_\_\_ ~~an eighth process for~~ removing said thin film element providing substrate having untransferred elements, from the final substrate to which said elements have been transferred.

4. (Canceled)

5. (Currently Amended) A manufacturing method for a device according ~~to claim~~ to claim 1, wherein ~~said fourth process~~ the exerting the force is performed by inserting a sharp edge body into one edge between said first substrate and said second substrate.

6. (Currently Amended) A manufacturing method for a device according ~~to claim~~ to claim 1, wherein ~~said fourth process~~ the exerting the force is performed by injecting a high pressure gas into one edge between said first substrate and said second substrate.

7. (Currently Amended) A manufacturing method for a device according ~~to claim~~ to claim 1, wherein ~~said fourth process~~ the exerting the force is performed by injecting a liquid into one edge between said first substrate and said second substrate.

8. (Currently Amended) A manufacturing method for a device according to claim 1, wherein ~~said fourth process~~ the exerting the force is performed by moving one of the edges of said first substrate and said second substrate in a direction to separate from the other of the edges of said first substrate and said second substrate.

9. (Currently Amended) A manufacturing method for a device according to claim 1, wherein ~~said~~ a thermal expansion material is provided in one edge of said separation layer when forming said separation layer in said first process, and ~~said fourth process~~ the exerting the force is performed by thermal expansion of said thermal expansion material by heat treatment.

10. (Previously Presented) A manufacturing method for a device according to claim 1, wherein said fourth process is performed by laser ablating said separation layer by irradiating laser light onto one edge between said first substrate and said second substrate.

11. (Previously Presented) A device obtained by a manufacturing method according to claim 1.

12. (Original) An electro-optic device provided with devices according to claim 11.

13. (Original) An electronic equipment provided with the devices according to claim 11.

14. (New) A manufacturing method for a device according to claim 1, wherein the step of adhering the elements to be transferred comprises:

forming a multilayer film comprising a protective layer, a photoabsorption layer, and the adhesive layer; and

adhering said elements to be transferred on said first substrate to said second substrate via the multilayer film.

15. (New) A manufacturing method for a device, comprising:

forming a separation layer on a first substrate;

forming elements on a separation layer;

adhering elements on said first substrate, to a second substrate via an adhesive layer;

exerting a force acting in a direction to separate said first substrate and said second substrate on the separation layer between said first substrate and said second substrate from one edge of those substrates, to execute at least one of internal exfoliation and interfacial exfoliation of the separation layer;

separating said first substrate from which the transfer of elements has been completed, from said second substrate;

forming after separating said first substrate from said second substrate, a heat fusion sheet containing heat sealing adhesive on said elements which have been transferred to said second substrate;

superposing a final substrate so that it contacts said heat fusion sheet, selectively radiating light only on an area of said elements to be transferred, and adhering only said elements to be transferred onto the final substrate for device forming; and

removing said heat fusion sheet having untransferred elements, from the final substrate to which said elements have been transferred.